UNIVERSITY OF WASHINGTON

SERVICES + ACTIVITIES FEE

Student Technology Loan Program
Kane Hall, Room 305
4069 Spokane Ln NE, Seattle, WA 98105

Greetings Student Technology Loan Program,

I am writing to officially inform you of the allocation made to the Student Technology Loan Program (STLP) for Fiscal Year 2027. After extensive deliberations, as well as consideration of your submitted documents and testimony, the Services & Activities Fee Committee agreed to recommend an allocation of **$267,534**. The recommendation was accepted by the Vice President for Student Life, Denzil Suite, and was approved by the Board of Regents during their May 14th meeting.

This year, increases in requests were close to $1.4m more than our projected increase in revenue. Despite this, after careful consideration of the increasing demand for the STLP's services, the Committee decided on an allocation representing a $9,106 increase over Fiscal Year 2026, reflecting your full request.

The Committee appreciates the time and effort you put into your budget request and presentation. The level of detail was very informative and helped to expedite the deliberations process. We also applaud your commitment to using our logo and to a consistent student staff presence in the SAF process.

The Committee thanks you for your cooperation with the SAF process, and we hope to continue working together in the future. It has been a pleasure working with you, and I wish you the best.

Sincerely,



Haley Chee
Chair, Services & Activities Fee Committee
University of Washington - Seattle